

ABSTRACT

With the mounting of semiconductor chips (1) on a substrate (3) having a solder portion (2) a semiconductor chip (4) held by a gripper (5) spring mounted on a bondhead (4) is lowered onto the substrate (3). In doing so, the gripper (5) is deflected towards the bondhead (4). Subsequently, the
5 semiconductor chip (1) is raised by a predetermined distance and then released. Optionally, the semiconductor chip (1) is moved up and down before being released. With this method, the semiconductor chip (1) is under mechanical control until the solder (2) has taken up a stable form and the semiconductor chip (1) has achieved its final position.

10 (Fig. 1C)

This Sheet Has Been Replaced

